

In the Claims

The claims have been amended as follows:

1. (currently amended) A method for reworking an electronic component with copper or copper/nickel pads containing a nickel layer and an overlying gold layer comprising the steps of:

supplying an electronic component having copper or copper/nickel pads thereon

containing a nickel layer and an overlying gold layer;

etching the gold layer on the component pads;

etching the nickel layer on the component pads;

treating the etched component to remove products formed during the etching steps

and corrosion products with a solution selected from the group consisting of a free

cyanide containing solution, chromic acid and a sodium hydroxide solution with a

periodic reverse current; and

plating the treated copper surface with a nickel layer followed by a gold layer.

2. (original) The method of claim 1 wherein the pads on the treated component are restored to their original condition by media blasting.

3. (original) The method of claim 2 wherein the gold layer is etched using a cyanide containing solution.

1 4. (original) The method of claim 3 wherein the nickel layer is etched using an
2 alkaline oxidizer containing solution having a pH greater than about 12.0.

1 5. (previously presented) The method of claim 4 wherein the etched component is
2 treated using a free cyanide containing solution.

1 6. (withdrawn) An apparatus for reworking an electronic component with copper or
2 copper/nickel pads containing a nickel layer and an overlying gold layer comprising:

3 supplying means to supply an electronic component having copper or copper/nickel
4 pads thereon containing a nickel layer and an overlying gold layer;

5 etching means to etch the gold layer on the component pads;

6 etching means to etch the nickel layer on the component pads;

7 treating means to remove products formed during the etching steps and corrosion
8 products from the etched component; and

9 plating means to plate the restored copper or copper/nickel pad surface with a nickel
10 layer and an overlying gold layer.

1 7. (withdrawn) The apparatus of claim 6 wherein the pads on the treated component
2 are restored to their original condition by media blasting.

1 8. (withdrawn) The apparatus of claim 7 wherein the gold layer etching means are a
2 cyanide containing solution.

1 9. (withdrawn) The apparatus of claim 8 wherein the nickel layer etching means is
2 an alkaline oxidizer containing solution having a pH greater than about 12.0.

1 10. (withdrawn) The apparatus of claim 9 wherein the treating means are a cyanide
2 containing solution.

1 11. (withdrawn) A reworked electronic component made using the method of claim
2 1.

1 12. (withdrawn) A reworked electronic component made using the method of claim
2 2.

1 13. (withdrawn) A reworked electronic component made using the method of claim
2 3.

1 14. (withdrawn) A reworked electronic component made using the method of claim
2 4.

1 15. (withdrawn) A reworked electronic component made using the method of claim
2 5.

1 16.-20. (canceled)